

ABSTRACT OF THE DISCLOSURE

An apparatus for forming a thin film on an article, wherein a film-forming gas is supplied from a gas supplying device to a vacuum container which can be evacuated by an exhausting device to reduce gas pressure in the container, an electric power is applied from a power applying device to the film-forming gas to produce plasma from the gas in which the thin film is formed on the article disposed in the vacuum container. The gas supplying device includes a gas supply member having a gas supply surface portion opposed to a film-forming surface of the article in the vacuum container. The gas supply member has a plurality of gas supply holes dispersedly formed at the gas supply surface portion. The power applying device includes a power applying electrode in the vacuum container, the electrode being disposed as opposed to a space between the article and the gas supply surface portion opposed to the article. The apparatus is capable of forming a thin film of high quality having a uniform thickness at a high deposition rate at an increased plasma density without increase of plasma potential.